Second S	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name	752-21.1											als and Mf	g Informati	on	
Semilar Semi	upplier Inform	ation													
Title - Contact Name Product Envis Compliance NA Product Envis Compliance NA Product Envis Ewards © nsemi.com Puthorized Representative* Title - Representative Product Envis Compliance NA Product Envis Ewards © nsemi.com Product En	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product Enviro Compliance Unitorized Representative* Title - Representative Title - Representative Product Enviro Compliance NA Product Enviro Compliance NA Product Enviro Compliance NA Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards NA Product Env-Stewards NA Product Env-Stewards NA Product Env-Stewards NA Nanufacturing Site Weight* UOM Unit T SCBE 18.79156 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Product Enviro Compliance NA NA Product Env-Stewards NA Nanufacturing Site Nan	nsemi											2024-05-14			
Title - Representative* Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number RS1JFA SR SOD123FA PN 0.8A 600V SR SOD123FA PN	ontact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product Envi-Stewards Requester Item Number Mfr Item Number Manufacturing Site Meight* Manufacturing Site Manufacturing Site Meight* Manuf	Product-Env-Stewa	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represer	ntative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
RS1JFA SR SOD123FA PN 0.8A 600V 2024-05-14 TSCBE 18.79156 mg Each Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles	Product-Env-Stewa	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Tomments See 1 - maximum time at peak temperature during soldering is 10-30 seconds	Requester	Requester Item Number Mfr I		m Number Mfr Item Name				Effective Date	Version	N	Anufacturing Site	V	Veight*	UOM	Unit Type
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or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
	Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.72998	mg	Supplier	Silicon (Si)	7440-21-3		0.657	mg
			В	Nickel (Ni)	7440-02-0		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0672	mg
Die Attach Solder	4.11996	mg	Supplier	Silver (Ag)	7440-22-4		0.103	mg
			A	Lead (Pb)	7439-92-1	7a	3.811	mg
			Supplier	Tin (Sn)	7440-31-5		0.206	mg
Lead Frame	6.79991	mg	Supplier	Iron (Fe)	7439-89-6		0.0068	mg
			Supplier	Copper (Cu)	7440-50-8		6.7911	mg
			Supplier	Phosphorus (P)	7723-14-0		0.002	mg
Mold Compound-Black	6.94164		Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.0725	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0715	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.715	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.0826	mg
Plating	0.20007	mg	Supplier	Tin (Sn)	7440-31-5		0.2001	mg